



## Material Content Data Sheet



Sales Product Name	TLD5542-1QV			Issued		14. November 2019		
MA#	MA005401464							
Package	PG-VQFN-48-31			Weight*		129.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.790	1.38	1.38	13847	13847
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		139	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11085	
	non noble metal	copper	7440-50-8	58.193	45.01	46.19	450090	461868
wire	non noble metal	copper	7440-50-8	0.629	0.49	0.49	4865	4865
encapsulation	organic material	carbon black	1333-86-4	0.190	0.15		1469	
	plastics	epoxy resin	-	8.041	6.22		62190	
	inorganic material	silicondioxide	60676-86-0	55.081	42.60	48.97	426023	489682
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20082	20082
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4748	4748
glue	plastics	epoxy resin	-	0.146	0.11		1129	
	noble metal	silver	7440-22-4	0.489	0.38	0.49	3779	4908
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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